IPC APEX 2019 is 1 month away!

(Albany, NY) 12/28/2018 – The IPC APEX 2019 trade show will take place at the San Diego Convention Center, in San Diego, CA, from January 29-31, 2019. Our team will be showcasing our wide range of specialized products as well as create solutions of your manufacturing needs. We hope to see you at Booth #1720 in North Hall, to learn more about YINCAE and these innovative products we have to offer.

This year YINCAE Advanced Materials offers premier products including our Solder joint encapsulant paste which can provide lower temperature soldering and be used at a higher temperature (300ºc). Our 50% filler nano-underfill can flow fast into small gaps (10m) at room temperature while our high-end underfills are fully compatible with flux residue and has zero gassing. We also offer Die Attach materials as well as Diamond Underfills. YINCAE continues to exceed customer expectations and develop specialized solutions for not only flip chip, CSP, BGA, POP, LGA, but also many more applications.

To schedule a meeting with the YINCAE team during the exhibition, please email us at: info@yincae.com with a brief description of the meeting topic and we will gladly reserve a time to see you. You can also find more information by visiting our website at: www.yincae.com. We hope to see you at the exhibition!

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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